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(54) **Title:** SINGLE SWITCH DIRECT COOLING ASSEMBLIES AND RELATED METHODS

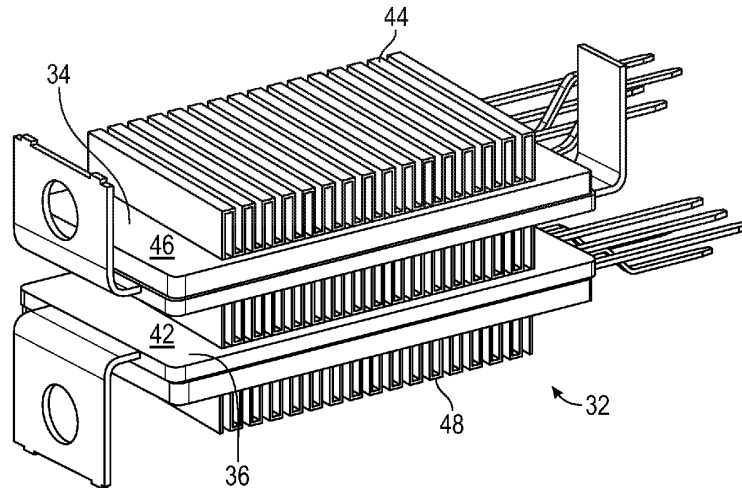


FIG. 7

(57) **Abstract:** Implementations of a dual sided cooling module may include a high side module coupled over a low side module through a coupling heat sink at a first largest planar surface of the high side module and at a first largest planar surface of the low side module; a high side heat sink coupled at a second largest planar surface of the high side module; and a low side heat sink coupled at a second largest planar surface of the low side module. A single cooling fluid may contact the coupling heat sink, the high side heat sink, and the low side heat sink.

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